BGA Questionnaire

Email: sales@topline.tv
Tel 1-800-776-9888
Fax 1-478-451-3000

Contact:

Name: ____

Company: ____

Email: ____

Project Ref:

Title: ____________________________________

Dept: ____________________________________

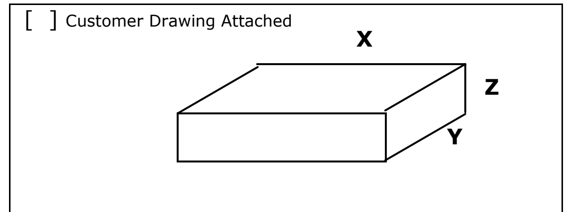
Tel: ______________________ Ext _______

Outline Size: [ ]mm [ ] µm [ ] mil [ ] inch

Substrate Size (Minimum): **X**= **Y**= **Z**=

Substrate Size (Maximum): **X**= **Y**= **Z**=

[ ] Customer Drawing Attached



Substrate Material:

[ ] BT [ ] FR4 [ ] Si [ ] Ceramic [ ] Pi [ ] Any

[ ] Other:

Ball Pitch (mm):

[ ] 0.3 [ ] 0.4 [ ] 0.5 [ ] 0.65 [ ] 0.75

[ ] 0.8 [ ] 1.0 [ ] 1.27 [ ] 1.5

Solder Ball Alloy:

[ ] SAC305 - Sn96.5/Ag3.0/Cu0.5

[ ] SnPb - Sn63/Pb37

[ ] Other _________

Solder Ball Diameter:

[ ] 0.20mm [ ] 0.45mm
[ ] 0.25mm [ ] 0.50mm
[ ] 0.30mm [ ] 0.63mm
[ ] 0.35mm [ ] 0.76mm
[ ] 0.40mm [ ] Other

Ball Count / Matrix [ ]Customer Drawing

[ ] Min Balls _______ [ ] Max Balls ______

[ ] Full Array [ ] Perimeter [ ] Custom

Matrix _______ x ________

Perimeter Rows Nbr:

Circuit Function:

[ ] Daisy Chain [ ] BUS [ ] Isolated Pads (No Daisy Chain)

[ ] Throughhole via test pads on top side

[ ] Any type available [ ] Other:

Packaging:

[ ] Tray [ ] Waffle Pack [ ] Tape & Reel

[ ] Any

[ ] Other ____________________________

Dummy Die:

Die Size: Min ________ Max ________ [ ] µm [ ] mil

Die Thick: Min ________ Max ________ [ ] µm [ ] mil

[ ] Die not required [ ] Any type available

Mounting of Die:
[ ] External (Flip Chip Style) [ ] Encapsulate (Internal)
[ ] Any type available

Pad Information:

Size: Min: ______ Max_____ [ ]µm [ ]mil

Plating: [ ] Ni-Au [ ] OSP [ ] Other:

[ ] Solder Mask Defined Pad

[ ] Non-Solder Mask Defined Pad

[ ] Other

Solder Mask:

[ ] Taiyo Model __________________ [ ] Any

[ ] Other

Part Number Series:

[ ] BGA [ ] PBGA [ ] LBGA
[ ] CBGA [ ] WLP [ ] SBGA
[ ] FBGA [ ] Any Type Available
[ ] Other: